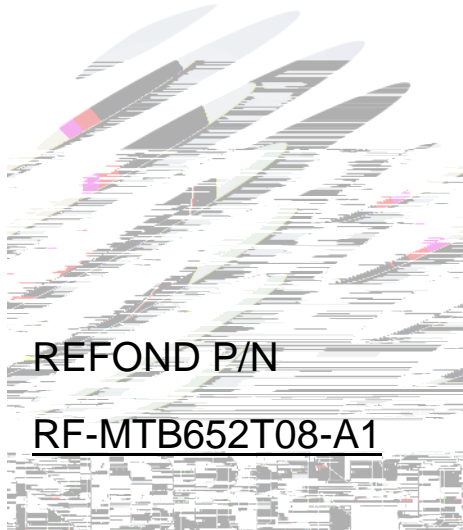


# SPECIFICATION



REFOND P/N

RF-MTB652T08-A1

R & D

Mass Product

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## 1. Product Description/

high reliability and high safety;

2835 LED Package, high lighting efficiency, low heat, without Mercury, belong to the environmental protection cold light source;

2835LED

The protection of the lamp is up to IP67, with beautiful appearance, no fouling situation.

IP67

Designed for normal and low temperature refrigeration walk-ins and display case applications;

Ideal for C-Stores, Grocery, and Big Box Retailers.



## 2.Product Specification /

### 2.1 Optical-electrical Characteristics(Absolute Maximum Ratings At Ts=25 )/

Tab.2-1Optical-electrical Characteristics

Refond PN	Customer PN	Module Characteristics				
		Current mA	Voltage(V)	Power(W)	Module LM	
		Typ	Typ	Typ	Min	Max
RF-MTB652T08-A1 6000-6500K	-	333	24	8± 8%	1000	1120
Color Rendering Index	80	(V)Test condition		Typ		
		24		24		
(MacAdamElipsis)				≤5		

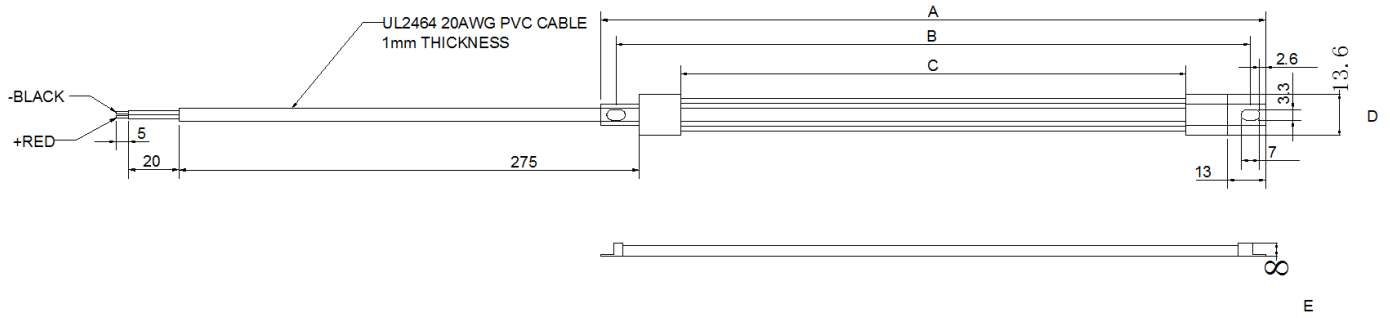
Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Forward Current	I <sub>F</sub>	333± 8%	mA
Peak Forward Current	I <sub>FP</sub>	435	mA
Reverse Voltage	V <sub>R</sub>	5	V
Electrostatic Discharge (HBM)	E <sub>SD</sub>	2000	V
Operating Temperature	T <sub>OPR</sub>	-40 ~ +85	
Storage Temperature	T <sub>STG</sub>	-40 ~ +100	
Junction temperature LED	T <sub>J</sub>	115	



### 3. Product Specification /

#### 3.1 Outline Dimension /



	Dimension
A	1629± 5mm
B	1616± 5mm
C	1580± 5mm
D	13.6± 1mm
E	8± 1mm



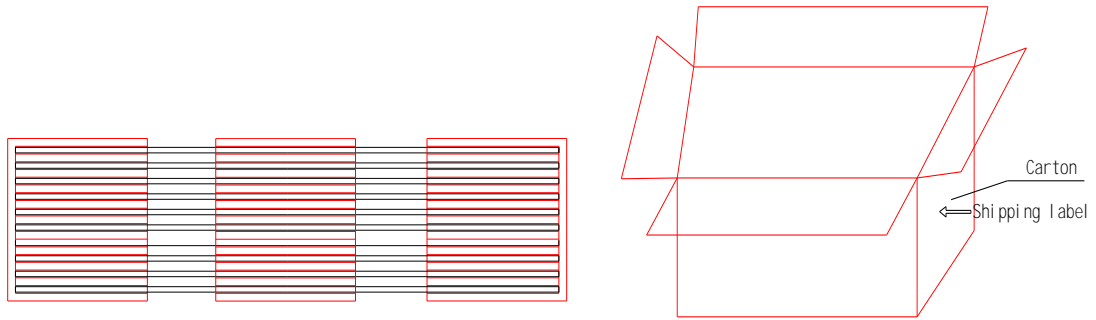




## 6.Packing Criterion/

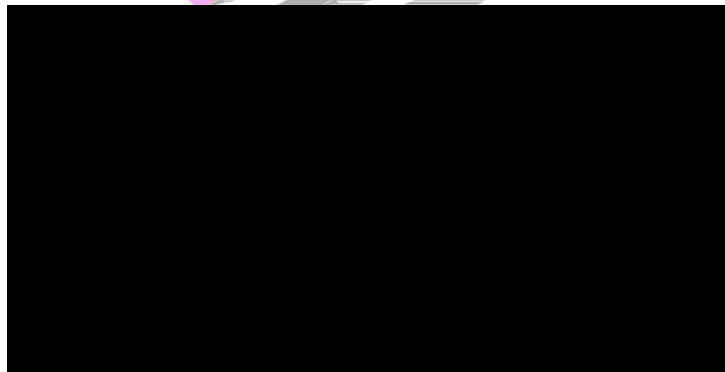
### 6.1 Package Diagram /

Fig 8-1Package Diagram /



### 6.2 Carton silk printing/

REFOND LOGOPay attention to identify



### 6.3Label Form Specification/



customer PN			
/P.N			
/BIN CODE		/LM	
/VF		/CCT	
/CRI		/QTY	
/N.W		/DATE	

## 7. Handling Precautions

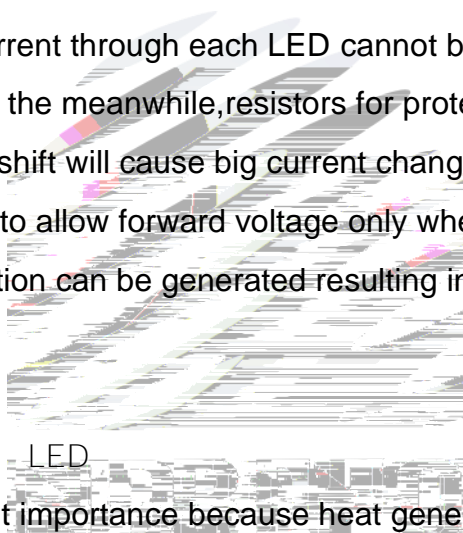


(4) Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



(5) In designing a circuit, the current through each LED cannot be exceeded the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED



LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause







Declare

This specification is written both in English and in Chinese and the latter is formal.